

MEC8-RA, MEC8-EM SERIES

(0.80 mm) .0315"

RIGHT-ANGLE/EDGE MOUNT SOCKETS

Mates with:
(1.60 mm) .062" thick card

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC8-RA

Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50 μm (1.27 μm) Ni
Operating Temp Range: -55 °C to +125 °C
Insertion Depth: (3.94 mm) .155" to (6.25 mm) .246"
Current Rating: 2.4 A per pin (2 adjacent pins powered)
Voltage Rating: 265 VAC
RoHS Compliant: Yes
Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MEC8 - **1** POSITIONS PER ROW - **02** PLATING OPTION - **D** - **RA1** - **OTHER OPTION**

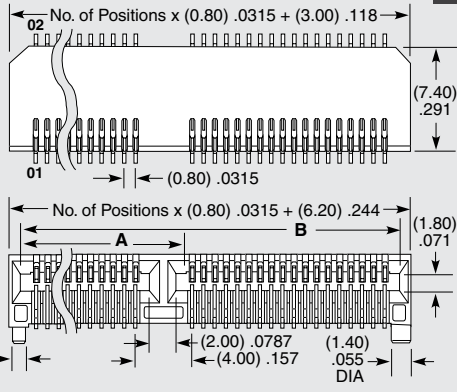
Note: Some sizes, styles and options are non-standard, non-returnable.

10, 13, 20, 25, 30, 37, 40, 49, 50

-L
= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail

-TR
= Tape & Reel Packaging

POS. PER ROW	A	B
13	(6.10) .240	(15.00) .591
25	(18.10) .713	(34.20) 1.346
37	(18.90) .744	(36.60) 1.441
40	(22.90) .902	(43.80) 1.724
49	(22.90) .902	(44.60) 1.756
50		



HIGH-SPEED CHANNEL PERFORMANCE

MEC8-RA
Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

14
Gbps

ALSO AVAILABLE (MOQ Required)

- 1 mm mating card thickness option
- Latching option
- Elevated Contact Samtec.

Mates with:
(1.60 mm) .062" thick card

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC8-EM

Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50 μm (1.27 μm) Ni
Operating Temp Range: -55 °C to +125 °C
Insertion Depth: (4.32 mm) .170" to (5.66 mm) .223"
Current Rating: 2.2 A per pin (2 adjacent pins powered)
Voltage Rating: 265 VAC
RoHS Compliant: Yes
Lead-Free Solderable: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

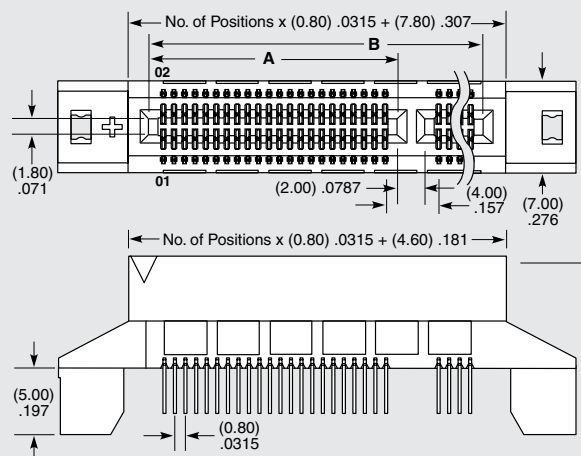


MEC8 - **1** POSITIONS PER ROW - **02** PLATING OPTION - **D** - **EM2**

10, 20, 30, 40, 50, 60, 70

-L
= 10 μm (0.25 μm) Gold on contact, Matte Tin on tail

EM2
= (1.60 mm) .062" thick PCB



HIGH-SPEED CHANNEL PERFORMANCE

MEC8-EM
Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

14
Gbps

POSITIONS PER ROW	A	B
40	(18.90) .744	(36.60) 1.441
50	(22.90) .902	(44.60) 1.756
60	(26.90) 1.059	(52.60) 2.071
70	(30.90) 1.217	(60.60) 2.386

ALSO AVAILABLE (MOQ Required)

- 1 mm mating card thickness option Contact Samtec.

Due to technical progress, all designs, specifications and components are subject to change without notice.